

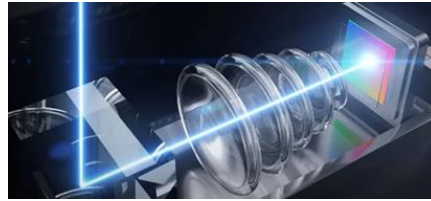


# Coverlay "C90 series"

—Low repulsion—

## Example of use

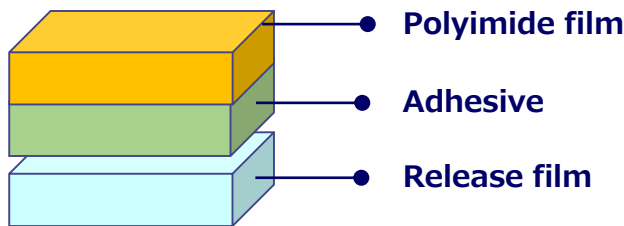
- Smartphone
- Tablet PC
- Digital camera



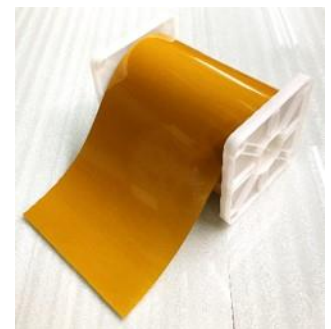
## Characteristics

- Can be folded and assembled because of its low repulsion & shape memory characteristics.
- High electrical insulation, applicable to fine line circuit (L/S=20/20).

## Product structure



## Product image



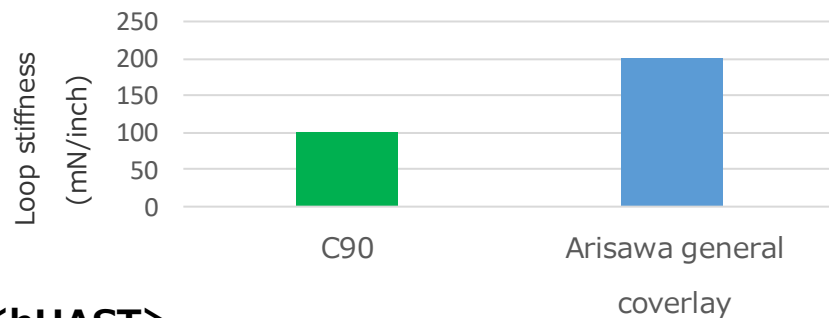
## Product Properties

Item	Unit	C90
90° Peel strength (Cu peeling)	N/cm	8
Solder heat resistance	°C	300
UL94 Flammability	-	Equivalent to V-0
Tg (Adhesive only)	°C	61
Elastic modulus (Adhesive only)	GPa	0.4

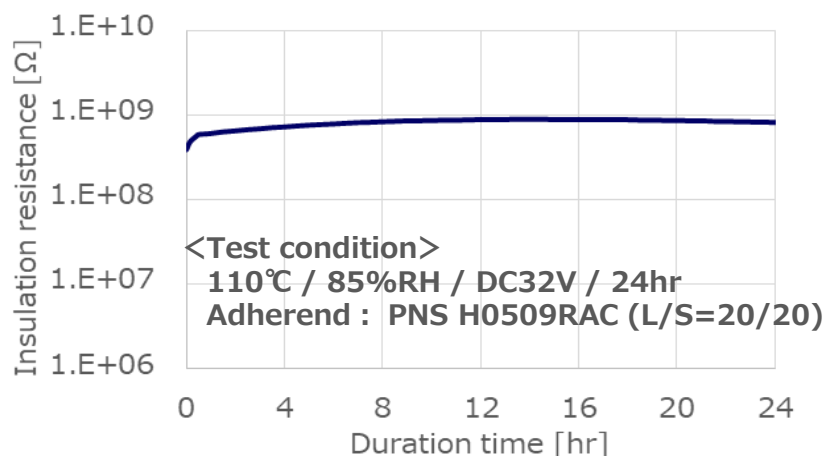
[Sample making conditions]

Pressing at 160°C×3MPa×60min

## <Repulsion test>



## <bHAST>



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The data in this document are measured values, not for guaranteed.